

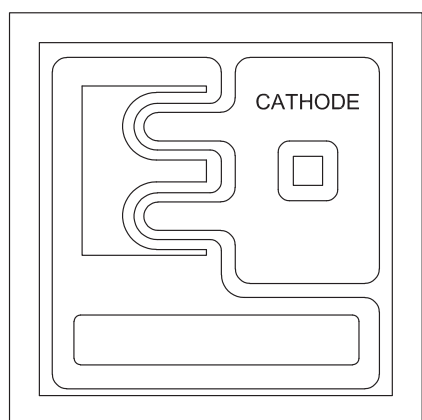
PROCESS CPZ40X
Transient Voltage Suppressor
5 Volt TVS Chip



PROCESS DETAILS

Die Size	13.4 x 13.4 MILS
Die Thickness	5.5 MILS
Cathode Bonding Pad Area	3.9 x 6.7 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 9,000Å

GEOMETRY



BACKSIDE ANODE R0

GROSS DIE PER 5 INCH WAFER

122,493

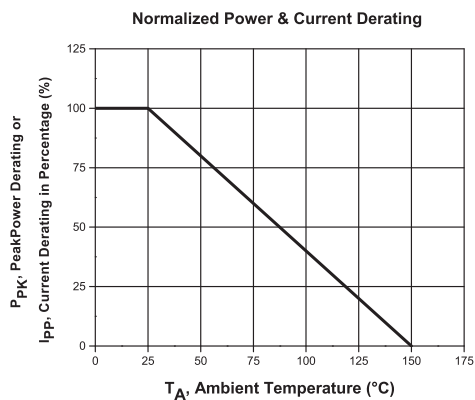
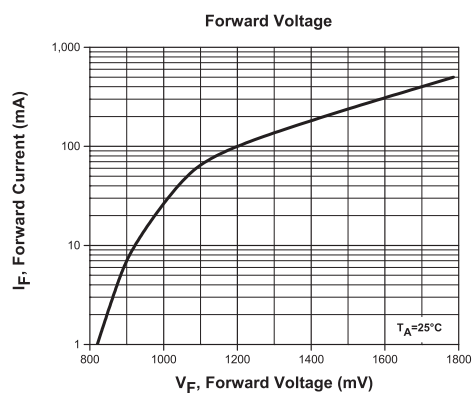
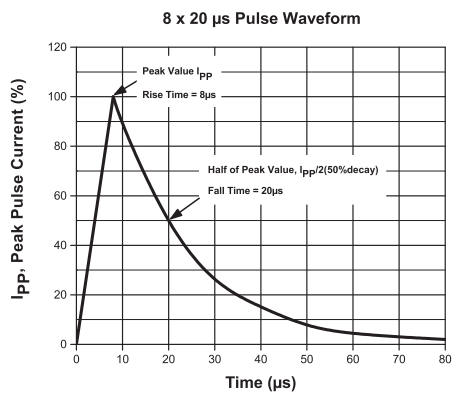
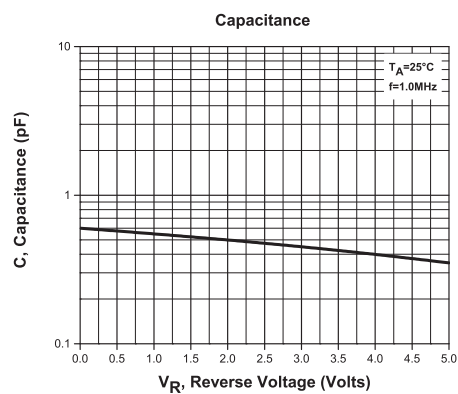
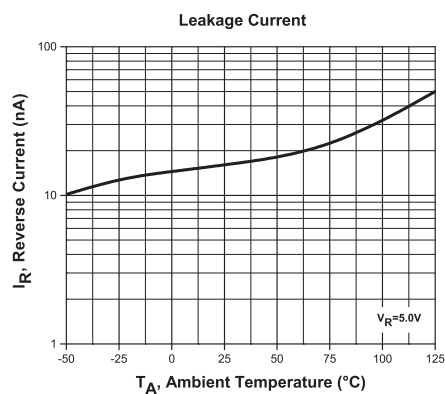
PRINCIPAL DEVICE TYPE

CMO5V0LC

R0 (9-January 2013)

PROCESS CPZ40X

Typical Electrical Characteristics



R0 (9-January 2013)